

T-6000-L/G

Customized Precision Die Bonding Solutions



The T-6000-L/G Die Bonder is a fully-automated all purpose system for R&D, pilot and medium size production. Equipped with linear motors and 0.1 μ m resolution glass scales, enable a precision of 4 μ m. A force range of 20g to 800g (optional 10g to 5kg), combined with the large working area of 400mm x 300mm and wafer handling up to 8", open a wide range of applications. With numerous available options, the T-6000-L/G can be customized to best suit your needs.

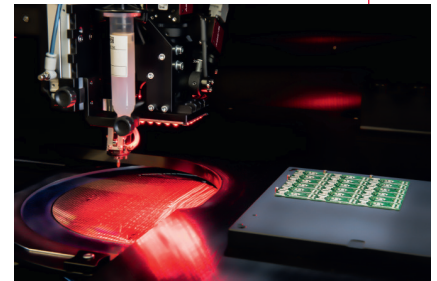
FEATURES AND OPTIONS FOR THE T-6000-L/G

- Granite Gantry
- Up looking camera
- Dispenser (Time/ Pressure or auger)
- Stamping unit
- Automatic tool changer (optional for heated tools)
- Eutectic bonding unit with protective gas chamber
- Customized substrate holders and fixtures available
- Wafer ring or wafer frame holders
- Automatic 3-D and force calibration
- Flux dipping station
- SMD feeder capability (8 and 12mm)
- Magazine Lifter
- Indexer (up to 6" width)

TECHNICAL DATA

XY-Movement (placement stage)	400mm x 300mm
XY-Movement (wafer stage)	220mm x 220mm
Z-Movement	100mm
Spindle Rotation	200° (100° with heated tools)
Bond Force (standard range)	15g- 800g (optional 15g to 5000g)
UPH	2000*
Placement Accuracy	2.5µm @ 3Sigma*
Axis Resolution	XYZ: 0.1µ,Theta: 0,02µ
Min./ Max. component size	250µm/ 20mm**
Wafer Pickup	2" to 8"
Connections	Compressed dry air 6 bar/Vacuum 0.9bar (abs.) min. 4.5m ³ /min
Dimensions	1360mm x 995mm x 1690mm
Weight	1100kg (approx.)
Voltage	220V-260V, 50Hz, 2.3kW (10A) 1phase
Environment	Room temp: 22°C +/- 2°C
Humidity	50%, +/-5%

* Process depending / ** Other dimensions on request
Note: All specifications are subject to change without notice



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